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TIDA-01405 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	PCB	1		TIDA-01405	Any	Printed Circuit Board	
2	C2, C6, C7, C8	4	22uF	C2012X7S1A226M125AC	TDK	CAP, CERM, 22 μ F, 10 V, +/- 20%, X7S, 0805	0805
3	C3	1	3300pF	GRM1885C1H332JA01D	MuRata	CAP, CERM, 3300 pF, 50 V, +/- 5%, COG/NP0, 0603	0603
4	C10	1	10uF	C3216X7R1E106M160AE	TDK	CAP, CERM, 10 μ F, 25 V, +/- 20%, X7R, 1206_190	1206_190
5	C11	1	68uF	TPSE686M025R0125	AVX	CAP, TA, 68 μ F, 25 V, +/- 20%, 0.125 ohm, SMD	7343-43
6	J1, J2, J3, J4, J5, J6, J7, J8, JP2	9		TSW-102-07-T-S	Samtec	Header, 2.54 mm, 2x1, Tin, TH	Header, 2.54 mm, 2x1, TH
7	JP1	1		TSW-103-07-T-S	Samtec	Header, 2.54 mm, 3x1, Tin, TH	Header, 2.54 mm, 3x1, TH
8	R1	1	12.4k	RC0603FR-0712K4L	Yageo America	RES, 12.4 k, 1%, 0.1 W, 0603	0603
9	R2	1	10.0k	RC0603FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.1 W, 0603	0603
10	R3	1	200	RC0603FR-07200RL	Yageo America	RES, 200, 1%, 0.1 W, 0603	0603
11	SH-JP1, SH-JP2	2	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
12	U1	1		TPS82130SILR	Texas Instruments	3-A 17V Step-down Converter Module with Integrated Inductor, SIL0008D (uSIP-8)	SIL0008D
13	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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